

# Apogee® Thermal Slide Debonder

## With DataStream™ Technology

Eliminate process variability and manual debonding risks with a semi-automated system designed for repeatability, substrate safety, and operational efficiency. Supports a wide range of adhesives, wafer sizes, and process scales.



*Serving the Semiconductor Industry Since 1987*

## BENEFITS

- NRTL listed for OSHA and ANSI compliance
- Fully automated debond sequence
- Dual heated platens
- Semi-automated wafer loading/unloading
- Recipe controlled substrate size change
- Enhanced logging with DataStream™ technology
- Compact and self contained

## SPECIFICATIONS

- Substrate sizes: 2 inch to 200 mm
- Max temperature: 300°C
- Temperature uniformity: 0.3% across working surface
- Independent platen temperature controls
- X-axis (debond) force: 1 to 100 N
- X-axis force resolution: 1 N
- X-axis maximum velocity: 20 mm/s
- Failsafe Z-axis force detection
- Z-axis resolution: 1 micron

## PROGRAMMABILITY

- Full-color touchscreen graphical user interface (GUI)
- Recipe control of temperatures, force, speed, and time
- Unlimited user-defined program steps for each recipe
- 0.1-second resolution for step times (time:0-9,999.9 s/step)
- Up/download DataStream™ process parameters via native USB and Ethernet ports
- Process logging and traceability for every wafer
- On-line graphical process charts
- Remote process management



## RELIABILITY

- Industry leading uptime
- 1-year full warranty on parts and labor
- Complimentary remote technical support for the life of the product
- Application process assistance for the life of the product

Total Throughput	Est. 8-14 WPH for ≤150mm diameter Est. 4-8 WPH for ≤200mm diameter
Qualified Wafer Materials	SiC, GaN, GaAs, InP, sapphire, silicon, glass, and more...
System Uptime	>99% over a 12-month period
Mean Time To Repair (MTTR)	< 24 hours
Mean Time Between Failures (MTBF; hours, cycles)	>600 hours, 6,000 cycles

## UTILITIES

- Voltage Ranges: 208-230VAC
- Power Requirements: 15.3A (max)
- Vacuum: 1/4" Push to Connect, <20" Hg (33kPa)
- Exhaust: 2" OD, 0.4" H<sub>2</sub>O @ 10CFM (100Pa @ 17CMH)
- N<sub>2</sub>/CDA: 1/4" Push to Connect, 70psi (482kPa)

## DIMENSIONS

- 38.7" (983mm) W x 40.2" (1022mm) D x 57" (1448mm) H
- Machine Weight 560 lb (208.7 kg) *excluding accessories*

## DATASTREAM™ TECHNOLOGY: CONNECTING THE SEMICONDUCTOR INDUSTRY

DataStream™ technology gives you access to all of your connected Apogee® manufacturing equipment in one place to track, access, and modify your systems via a web browser. This technology provides manufacturers with the ability to process and visualize data in real time and search and export that data into a number of different formats.

### Real-Time Process Information

- Constant feedback of process information for monitoring critical process parameters
- Streamlined interface between different process modules
- Visual cues on process status & health

### Environmental Monitoring

- Monitoring of temperature & humidity allows for stricter control of critical processes
- Set preconditions and tolerances for monitored parameters
- On-screen, colored visual cues for deviation from controlled specs

### Advanced Recipe Creation

- Seamless switching between basic and advanced recipe creation methods
- Plain-English recipe translation
- Predefined process commands
- Unlimited process steps
- Unlimited recipe storage

### Data Logging & Export

- Export data logs into commonly readable formats for further analysis and process troubleshooting
- Increase process efficiency
- Identify process control deviations
- Analyze multiple processes for best known method (BKM) development

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